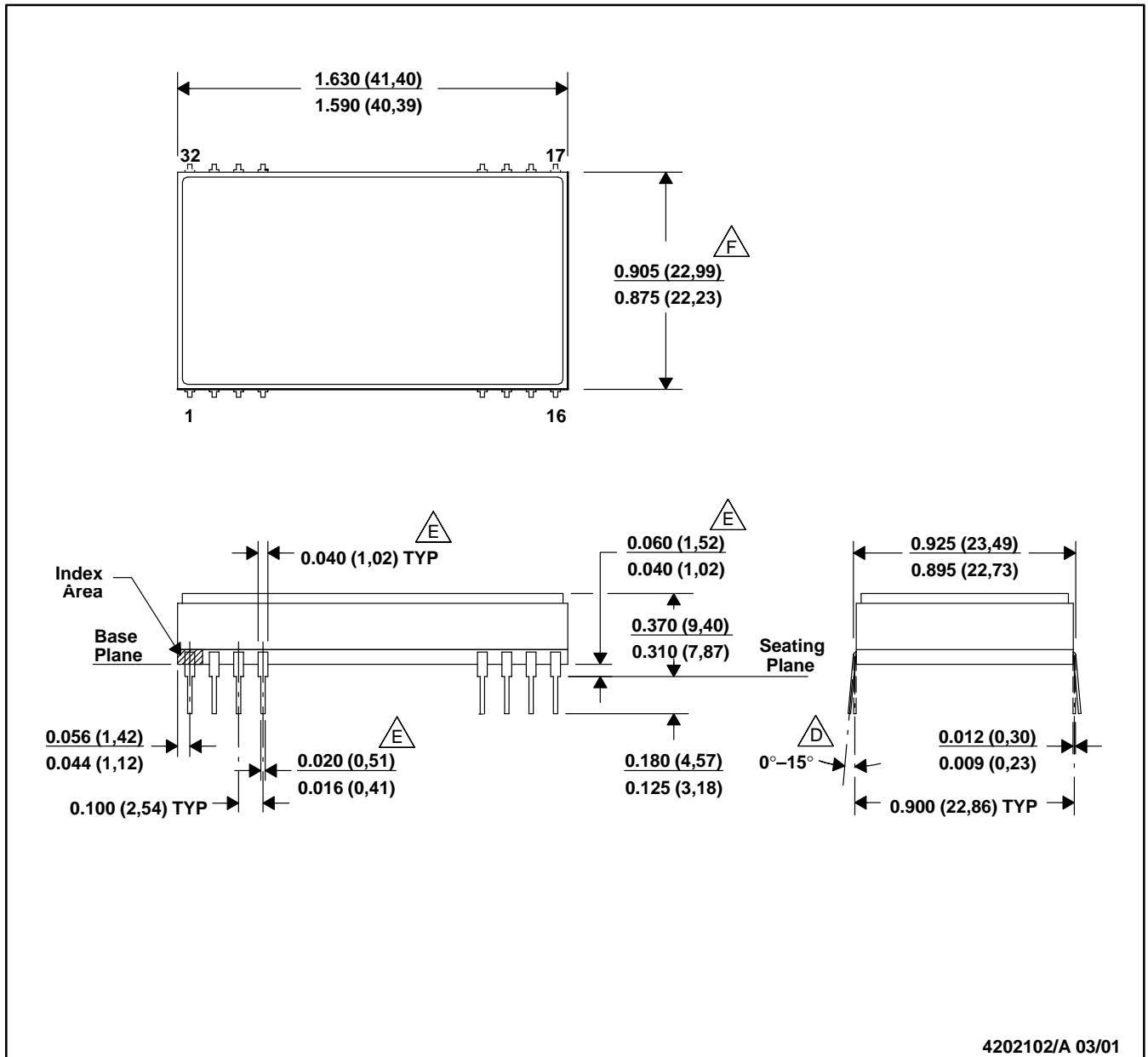


JVF (R-CDIP-T16/32)

CERAMIC SIDE-BRAZE DUAL-IN-LINE



4202102/A 03/01

- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Leads within 0.005 (0,13) radius of true position (TP) at gage plane with maximum material condition and unit installed.
 D. Angle applies at spread leads prior to installation.
 E. Outlines on which the seating plane is coincident with the plane (standoff = 0), terminals lead standoffs are not required, and the lead shoulder may equal lead width along any part of the lead above the seating/base plane.
 F. Body width dimension does not include particles of packing materials.
 G. A visual index feature must be located within the cross-hatched area.

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